

Appl. No. 10/575,510  
Amdt. dated Aug. 14, 2007  
Reply to Office Action of May 14, 2007  
Attorney Docket No. 1217-060907

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.	:	10/575,510	Confirmation No. 3919
Applicants	:	Koichi NAGAMOTO et al.	
Filed	:	April 13, 2006	
Title	:	Surface-Protecting Sheet and Semiconductor Wafer Lapping Method	
Art Unit	:	3723	
Examiner	:	Dung V. Nguyen	
Customer No.	:	28289	

MAIL STOP AMENDMENT  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

AMENDMENT

Sir:

In response to the Office Action of May 14, 2007, please amend the above-identified application as follows:

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 3 of this paper.

**Remarks** begin on page 7 of this paper.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on August 14, 2007.

\_\_\_\_\_  
Diane Paul

(Name of Person Mailing Paper)

\_\_\_\_\_  
*Diane Paul*  
Signature

\_\_\_\_\_  
08/14/2007  
Date